

July 10, 2013

Entegris' Full Suite of 450mm Wafer Handling Products Selected by Global 450mm Consortium at SUNY's NanoCollege

ALBANY, N.Y. and BILLERICA, Mass., July 10, 2013 (GLOBE NEWSWIRE) -- Entegris, Inc. (Nasdaq:ENTG) announced that its handling and shipping products for the safe, reliable transport and processing of 450mm wafers were selected by the Global 450mm Consortium (G450C), headquartered at SUNY's College of Nanoscale Science and Engineering (CNSE) in Albany, New York, for use in the development of 450mm wafer technology.

A photo accompanying this release is available at http://www.globenewswire.com/newsroom/prs/?pkgid=19821

G450C is a public-private partnership announced by New York Governor Andrew M. Cuomo in September 2011 to facilitate the 450mm wafer size transition. It is spearheaded by CNSE in partnership with Intel, IBM, GlobalFoundries, Samsung and TSMC. The new 450mm cleanroom is located at CNSE's Albany NanoTech Complex within the NanoFab Xtension (NFX) expansion.

The Entegris products selected by the G450C comprise a comprehensive wafer handling solution that includes 450mm Multiple Application Carriers (MAC), 450mm Front Opening Pod (FOUP), 450mm Single Wafer Shippers (SWS), and an innovative packaging system. As part of its agreement with the G450C, Entegris has agreed to provide on-site service which will allow G450C to fully leverage Entegris' industry recognized expertise in engineering wafer handling solutions, ensuring G450C maximizes efficiency and accelerates the proliferation of 450mm processes.

Paul Farrar Jr., CNSE Vice President for Manufacturing Innovation and General Manager of G450C, said, "Under the leadership and vision of Governor Andrew Cuomo, New York is firmly established as the hub for the critical industry evolution to 450mm wafer technology. We look forward to working closely with Entegris and to utilizing its capabilities to help enable the important transition to 450mm technology."

Bill Shaner, vice president and general manager for Entegris' Microenvironments Division, said: "As the industry pioneer in wafer shipping and wafer processing products, it was important for Entegris to collaborate with G450C, which is leading the global transition to 450mm wafer technology, to provide early solutions for transporting these larger wafers. Our 450mm development efforts, which began in 2007, have resulted in innovative and differentiated technology that will serve the needs of the industry's leading companies as they ramp up 450mm operations."

About G450C

The G450C is a public-private partnership program comprised of New York State (CNSE), Intel, TSMC, Samsung, IBM and GLOBALFOUNDRIES that develops cost-effective test wafer fabrication infrastructure, equipment prototypes and high-volume tools to enable a coordinated industry transition to 450mm wafers. The program uses the capabilities established at CNSE for joint development activities and support of a comprehensive industry ecosystem. Additional information can be found at www.g450c.org.

About Entegris

Entegris is a leading provider of a wide range of products for purifying, protecting and transporting critical materials used in processing and manufacturing in the semiconductor and other high-tech industries. Entegris is ISO 9001 certified and has manufacturing, customer service and/or research facilities in the United States, China, France, Germany, Israel, Japan, Malaysia, Singapore, South Korea and Taiwan. Additional information can be found at www.entegris.com.

The photo is also available at Newscom, www.newscom.com, and via AP PhotoExpress.

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Entegris' Multiple Application Carrier (MAC) solution for the handling of 450 mm semiconductor wafers.